

What is claimed is:

- 1 1. A printed circuit board (PCB) comprising:
2 a dielectric board member; and
3 a first signal line supported on said dielectric board member, said first signal
4 line including an elongated conductive member that is enshrouded with a carbon-based
5 cladding over at least a portion of its length.
- 1 2. The PCB of claim 1, comprising:
2 a second signal line supported on said dielectric board member, said second
3 signal line including a second elongated conductive member that is enshrouded with
4 a carbon-based cladding over at least a portion of its length, said second signal line
5 being adjacent to said first signal line.
- 1 3. The PCB of claim 2, wherein:
2 said carbon-based cladding of said second signal line is continuous with said
3 carbon-based cladding of said first signal line.
- 1 4. The PCB of claim 2, wherein:
2 said carbon-based cladding of said second signal line is discontinuous with said
3 carbon-based cladding of said first signal line.
- 1 5. The PCB of claim 1, comprising:
2 a second dielectric board member disposed above said first dielectric board
3 member and said first signal line.
- 1 6. The PCB of claim 1, wherein:
2 said elongated conductive member is fully covered over top, bottom and side
3 portions thereof with said carbon-based cladding for said at least a portion of its length.

1 13. The PCB of claim 9 wherein:
2 said first metallic member includes metallic plating within a plated through-
3 hole.

1 14. The PCB of claim 9 wherein:
2 said first and second metallic members each include an elongated signal line
3 conductor.

1 15. A multi-layer printed circuit board (PCB) comprising:
2 a first dielectric board member having a signal line supported thereon;
3 a second dielectric board member having a conductive terminal member
4 supported thereon; and
5 a plated through-hole extending through said first and second dielectric board
6 members, said plated through-hole including a metallic plating covering a carbon-based
7 cladding adhered to an inner surface of said through-hole;
8 wherein said signal line is conductively coupled to said metallic plating of said
9 plated through-hole through a portion of said carbon-based cladding, said portion of
10 said carbon-based cladding to provide a finite electrical resistance between said signal
11 line and said conductive terminal member within an electrical circuit to be formed
12 using said multi-layer PCB.

1 16. The multi-layer PCB claimed in claim 15, wherein:
2 said signal line includes an elongated conductive member that is enshrouded
3 with a carbon-based cladding over at least a portion of its length.

1 17. The multi-layer PCB claimed in claim 15, wherein:
2 said conductive terminal member forms a ground terminal on said second
3 dielectric board member, said finite electrical resistance to act as a pull-down resistance
4 within said electrical circuit.

1 18. The multi-layer PCB claimed in claim 15, wherein:

2 said conductive terminal member forms a supply terminal on said second
3 dielectric board member, said finite electrical resistance to act as a pull-up resistance
4 within said electrical circuit.

1 19. An electrical subsystem comprising:

2 a printed circuit board (PCB) including at least one dielectric board member
3 having a plurality of conductive interconnects for providing circuit interconnections
4 within said electrical subsystem, said plurality of conductive interconnects including
5 at least one interconnect that is enshrouded with a carbon-based cladding over at least
6 a portion thereof; and

7 a plurality of external electrical components coupled to said plurality of
8 conductive interconnects of said PCB to form an electrical circuit.

1 20. The electrical subsystem of claim 19, wherein:

2 said electrical subsystem is a computer processor board and said plurality of
3 electrical components includes at least one digital processing device.

1 21. The electrical subsystem of claim 19, wherein:

2 said at least one interconnect is adjacent to another interconnect on said at least
3 one dielectric board member, said carbon-based cladding to reduce noise coupling
4 between said at least one interconnect and said another interconnect.

1 22. The electrical subsystem of claim 19, wherein:

2 said at least one interconnect is covered with said carbon-based cladding over
3 top, bottom, and side portions thereof.

1 23. The electrical subsystem of claim 19, wherein:
2 a portion of said carbon-based cladding provides a finite electrical resistance
3 between two conductive interconnects of said PCB, said finite electrical resistance to
4 be used as a circuit element within said electrical circuit.

1 24. A method for manufacturing a printed circuit board (PCB) comprising:
2 providing a dielectric board member;
3 depositing a carbon-based cladding on an upper surface of said dielectric board
4 member;
5 adding a metallic layer to an upper surface of said carbon-based cladding;
6 processing said metallic layer to produce a predetermined metallization pattern
7 on said carbon-based cladding; and
8 depositing additional carbon-based cladding over at least a portion of said
9 predetermined metallization pattern.

1 25. The method claimed in claim 24, comprising:
2 removing carbon-based cladding from a region between two signal lines of said
3 predetermined metallization pattern to expose a portion of said upper surface of said
4 dielectric board member.

1 26. The method claimed in claim 24, comprising:
2 providing a second dielectric board member; and
3 placing said second dielectric board member over said additional carbon-based
4 cladding.

1 27. The method claimed in claim 24, wherein:
2 depositing a carbon-based cladding includes applying a carbon black material
3 to said upper surface of said dielectric board member.

- 1 28. The method claimed in claim 24, wherein:
2 said dielectric board member includes a glass-reinforced epoxy material.
- 1 29. The method claimed in claim 24, wherein:
2 processing said metallic layer includes using photolithography techniques.